Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	10/615298	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/30 07:24
L2	515	((osamu near furukawa) (toshihiko near murata) (psamu near ikata)). in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2007/08/30 07:25
L3	. 649	((osamu near furukawa) (toshihiko near murata) (osamu near ikata)). in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON ·	2007/08/30 07:32
L4		10/959411	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/30 07:51
L5	10	("6777819" "6784765" "20010006456" "6713375" "6794747").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/30 08:08
L6	20	("6777819" "6784765" "20010006456" "6713375" "6794747" "6404303" "6633005" "6424541" "6057954" "20040032706" "6784765" "20010006456" "6777819").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/30 13:15
L7	2063	361/760.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/30 09:15
L8	171	7 and (bonding near wire) and (flip-chip flipchip flip adj chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/30 12:25

L9	13	("5570274"   "5615089"   "5795799"   "5808878"   "5844315"   "6049467"   "6223429"   "6340839"   "6424034"   "6597062"   "6700196"   "6833628"   "6919620").PN. OR ("7208824"). URPN.	US-PGPUB; USPAT; USOCR	OR .	ON	2007/08/30 09:25
L10	14	("5070258"   "5422514"   "5498901"   "5570274"   "5696403"     "5748452"   "5796164"   "5963490"   "6222274").PN. OR ("6340839"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/30 09:29
L11	23	("4616655"   "5391917"   "5477082"   "5798567"   "6137164"   "6166443"   "6201266"   "6201302"   "6229215"   "6239484").PN. OR ("6437990").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/30 09:37
L12	35	("4349862"   "4437141"   "4574255"   "4616655"   "4759056"   "4780795"   "4800459"   "4811082"   "4882657"   "4975765"   "5110664"   "5166772"   "5220488"   "5225969"   "5235496"   "5237204"   "5239198"   "5293067"   "5306948"   "5309326"   "5355016"   "5428885"   "5471368"   "5481432"   "5557142"   "5714239"   "5793105"   "5854534").PN. OR ("6418030"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/30 09:43
L13	18	("5018051"   "5031069"   "5150280").PN. OR ("5235496"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/30 12:24
L14	3031	361/728,748,749.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/30 12:25
L15	2767	14 not 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR '	ON	2007/08/30 12:28
L16	65	15 and (bonding near wire) and (flip-chip flipchip flip adj chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/30 12:28

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L17	2720	361/763-765,767,783.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2007/08/30 12:28
L18	2056	17 not (14 7)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2007/08/30 12:28
L19	140	18 and (bonding near wire) and (flip-chip flipchip flip adj chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/30 13:19
L20	37	("20010008776"   "20020017721"   "20020025608"   "20020074669"   "20020175421"   "20020195270"   "4951232"   "5424573"   "5475264"   "5616957"   "5642262"   "5784264"   "5807791"   "5872051"   "5872700"   "5977626"   "5986886"   "5999437"   "6069793"	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/30 12:49
•		"6075289"   "6157080"   "6208525"   "6239482"   "6294731"   "6297551"   "6335221"   "6376907"   "6392896"   "6414385"   "6437984"   "6475830"				
		"6608763"   "6618267"   "6630727"   "6703698"   "6734552"     "6849940").PN. OR ("7215022").   URPN.		=		
L21	2	"20020195704".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/30 12:50
L22	16	(US-20010002163-\$ or US-20020175421-\$ or US-20020195704-\$).did. or (US-6340839-\$ or US-7208824-\$ or US-6437990-\$ or US-5235496-\$ or US-5150280-\$ or US-5949654-\$ or US-7215022-\$ or US-6630727-\$ or US-5999437-\$ or US-5475264-\$ or US-7176579-\$ or US-6407456-\$ or US-5495398-\$).did.	US-PGPUB; USPAT	OR	ON	2007/08/30 13:14

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L23	0	22 and (SAW surface adj acoustic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/30 13:15
L24	8	6 and (SAW surface adj acoustic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/30 13:19
L25	4421	257/723-725.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/30 13:18
L26	8	24 and (SAW surface adj acoustic)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/30 13:19
L27	3	26 and (bonding near wire) and (flip-chip flipchip flip adj chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/30 14:37
L28	0	((substrate) and (surface adj acoustic) and (face adj (up down)) and ((semiconductor adj chip) near10 (up down)) and (ripples near4 characteristic)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/30 14:40